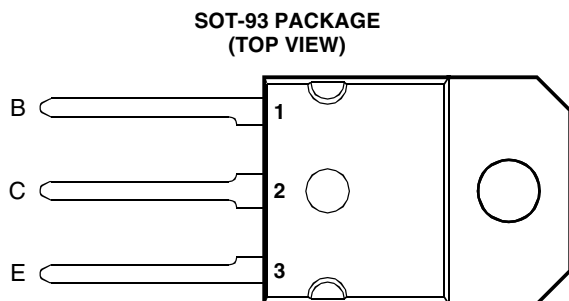


**BOURNS®**

- Rugged Triple-Diffused Planar Construction
- 15 A Continuous Collector Current
- 1000 Volt Blocking Capability



Pin 2 is in electrical contact with the mounting base.

MDTRAAA

**absolute maximum ratings at 25°C case temperature (unless otherwise noted)**

RATING		SYMBOL	VALUE	UNIT
Collector-emitter voltage ( $V_{BE} = 0$ V)	BUV48	$V_{CES}$	850	V
	BUV48A		1000	
Collector-emitter voltage ( $R_{BE} = 10 \Omega$ )	BUV48	$V_{CER}$	850	V
	BUV48A		1000	
Collector-emitter voltage ( $I_B = 0$ )	BUV48	$V_{CEO}$	400	V
	BUV48A		450	
Continuous collector current		$I_C$	15	A
Peak collector current (see Note 1)		$I_{CM}$	30	A
Continuous base current		$I_B$	4	A
Peak base current		$I_{BM}$	20	A
Non repetitive accidental peak surge current		$I_{CSM}$	55	A
Continuous device dissipation at (or below) 25°C case temperature		$P_{tot}$	125	W
Operating junction temperature range		$T_j$	-65 to +150	°C
Storage temperature range		$T_{stg}$	-65 to +150	°C

NOTE 1: This value applies for  $t_p \leq 2$  ms, duty cycle  $\leq 2\%$ .

**PRODUCT INFORMATION**

AUGUST 1978 - REVISED SEPTEMBER 2002  
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# BUV48, BUV48A

## NPN SILICON POWER TRANSISTORS

**BOURNS®**

### electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
$V_{CE(sus)}$ Collector-emitter sustaining voltage	$I_C = 200 \text{ mA}$	$L = 25 \text{ mH}$	(see Note 2)	BUV48 400			V
$I_{CES}$ Collector-emitter cut-off current	$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$		BUV48		0.2	mA
	$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$		BUV48A		0.2	
	$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$	$T_C = 125^\circ\text{C}$	BUV48		2.0	
	$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$	$T_C = 125^\circ\text{C}$	BUV48A		2.0	
$I_{CER}$ Collector-emitter cut-off current	$V_{CE} = 850 \text{ V}$	$R_{BE} = 10 \Omega$		BUV48		0.5	mA
	$V_{CE} = 1000 \text{ V}$	$R_{BE} = 10 \Omega$		BUV48A		0.5	
	$V_{CE} = 850 \text{ V}$	$R_{BE} = 10 \Omega$	$T_C = 125^\circ\text{C}$	BUV48		4.0	
	$V_{CE} = 1000 \text{ V}$	$R_{BE} = 10 \Omega$	$T_C = 125^\circ\text{C}$	BUV48A		4.0	
$I_{EBO}$ Emitter cut-off current	$V_{EB} = 5 \text{ V}$	$I_C = 0$				1	mA
$V_{EBO}$ Emitter-base breakdown voltage	$I_E = 50 \text{ mA}$	$I_C = 0$		7		30	V
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$		BUV48		1.5	V
	$I_B = 3 \text{ A}$	$I_C = 15 \text{ A}$	(see Notes 3 and 4)	BUV48		5.0	
	$I_B = 1.6 \text{ A}$	$I_C = 8 \text{ A}$		BUV48A		1.5	
	$I_B = 2.4 \text{ A}$	$I_C = 12 \text{ A}$		BUV48A		5.0	
$V_{BE(sat)}$ Base-emitter saturation voltage	$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$	(see Notes 3 and 4)	BUV48		1.6	V
	$I_B = 1.6 \text{ A}$	$I_C = 8 \text{ A}$		BUV48A		1.6	
$f_t$ Current gain bandwidth product	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ MHz}$		10		MHz
$C_{ob}$ Output capacitance	$V_{CB} = 20 \text{ V}$	$I_C = 0$	$f = 1 \text{ MHz}$		150		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques,  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

### thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1	$^\circ\text{C}/\text{W}$

### resistive-load-switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
$t_{on}$ Turn on time	$I_C = 10 \text{ A}$	$V_{CC} = 150 \text{ V}$	BUV48 (see Figures 1 and 2)			1.0	$\mu\text{s}$
$t_s$ Storage time						3.0	$\mu\text{s}$
$t_f$ Fall time						0.8	$\mu\text{s}$
$t_{on}$ Turn on time	$I_C = 8 \text{ A}$	$V_{CC} = 150 \text{ V}$	BUV48A (see Figures 1 and 2)			1.0	$\mu\text{s}$
$t_s$ Storage time						3.0	$\mu\text{s}$
$t_f$ Fall time						0.8	$\mu\text{s}$

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

### inductive-load-switching characteristics at 100°C case temperature

PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
$t_{sv}$ Voltage storage time	$I_C = 10 \text{ A}$	$I_{B(on)} = 2 \text{ A}$	BUV48 (see Figures 3 and 4)			4.0	$\mu\text{s}$
$t_{fi}$ Current fall time						0.4	$\mu\text{s}$
$t_{sv}$ Voltage storage time	$I_C = 8 \text{ A}$	$I_{B(on)} = 1.6 \text{ A}$	BUV48A (see Figures 3 and 4)			4.0	$\mu\text{s}$
$t_{fi}$ Current fall time						0.4	$\mu\text{s}$

**PRODUCT INFORMATION**



PARAMETER MEASUREMENT INFORMATION

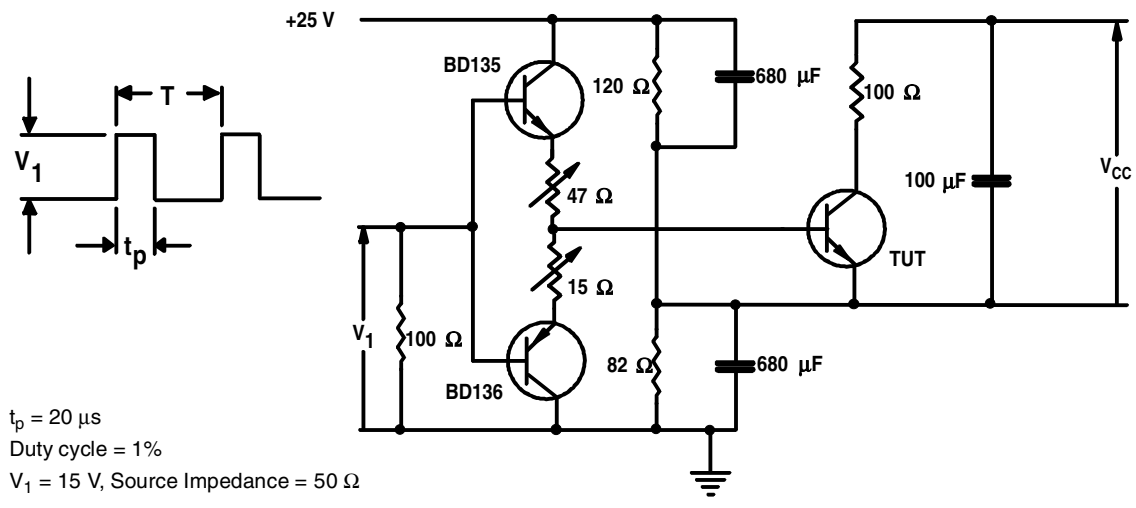


Figure 1. Resistive-Load Switching Test Circuit

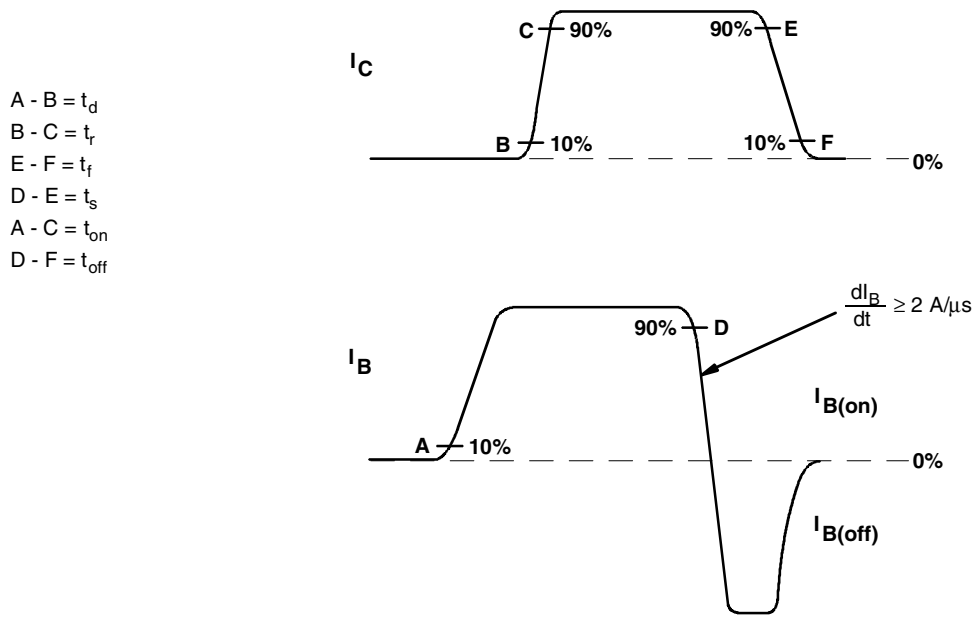
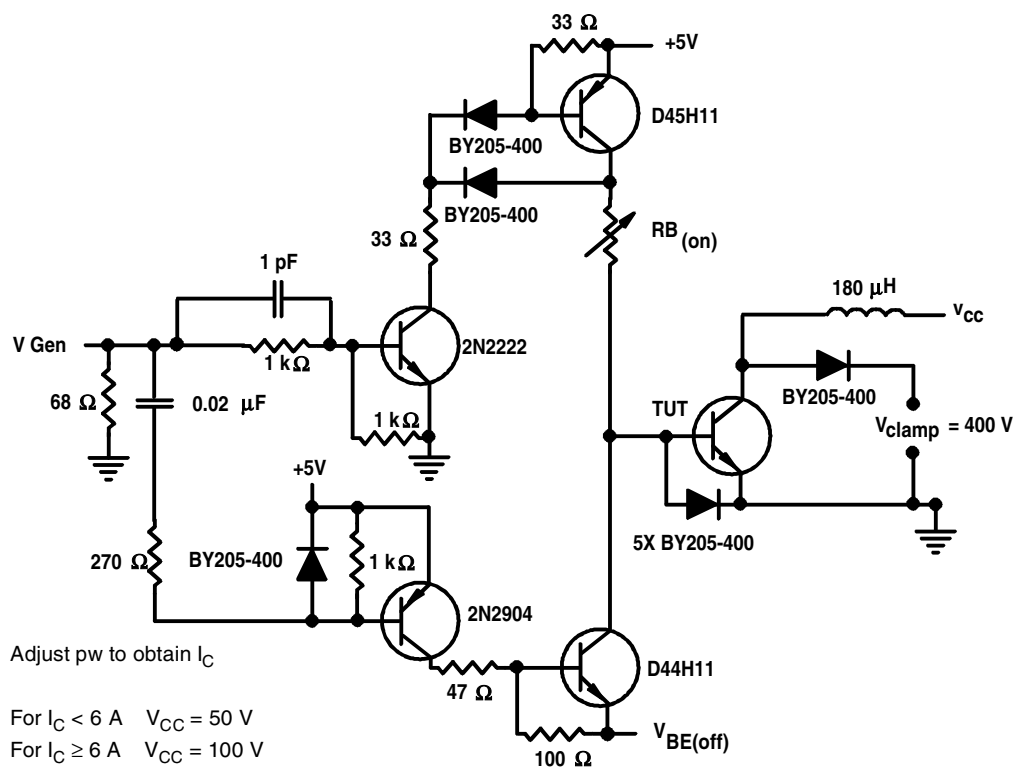
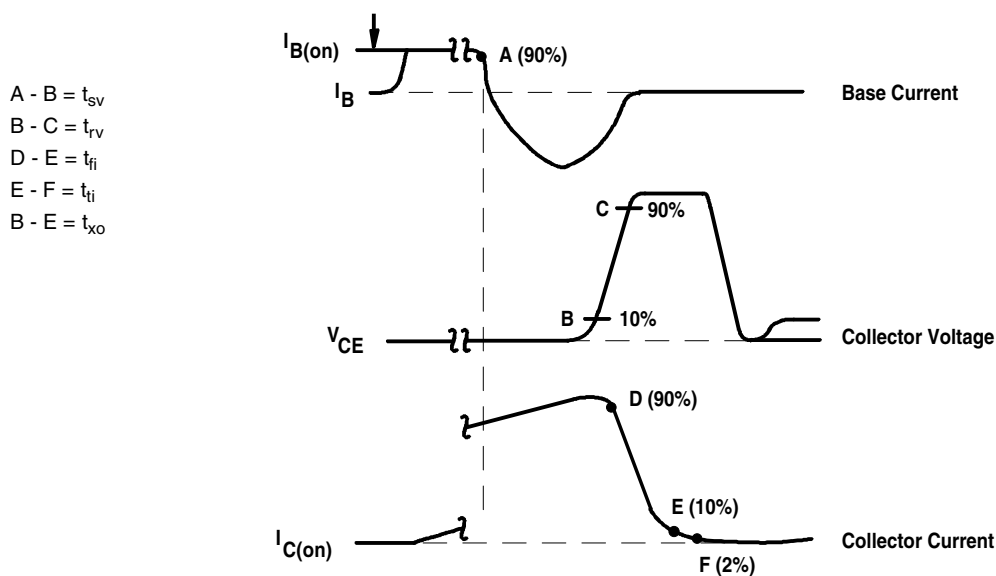


Figure 2. Resistive-Load Switching Waveforms

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**PARAMETER MEASUREMENT INFORMATION**

**Figure 3. Inductive-Load Switching Test Circuit**


NOTES: A. Waveforms are monitored on an oscilloscope with the following characteristics:  $t_r < 15 \text{ ns}$ ,  $R_{in} > 10 \Omega$ ,  $C_{in} < 11.5 \text{ pF}$ .  
 B. Resistors must be noninductive types.

**Figure 4. Inductive-Load Switching Waveforms**



TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN  
VS  
COLLECTOR CURRENT

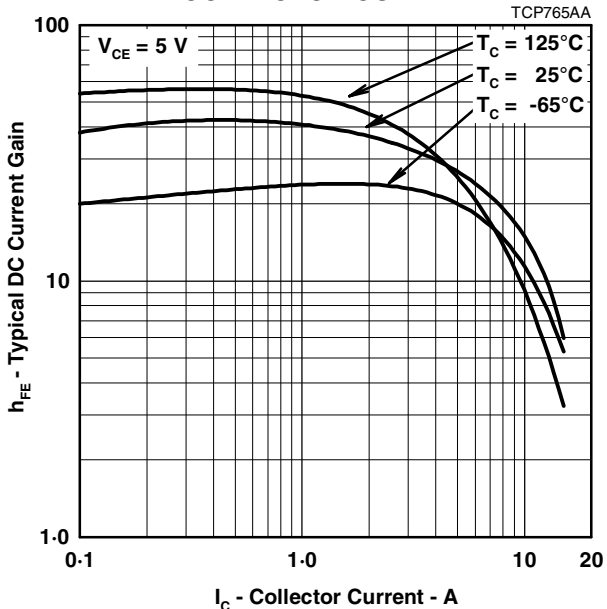


Figure 5.

COLLECTOR-EMITTER SATURATION VOLTAGE  
VS  
BASE CURRENT

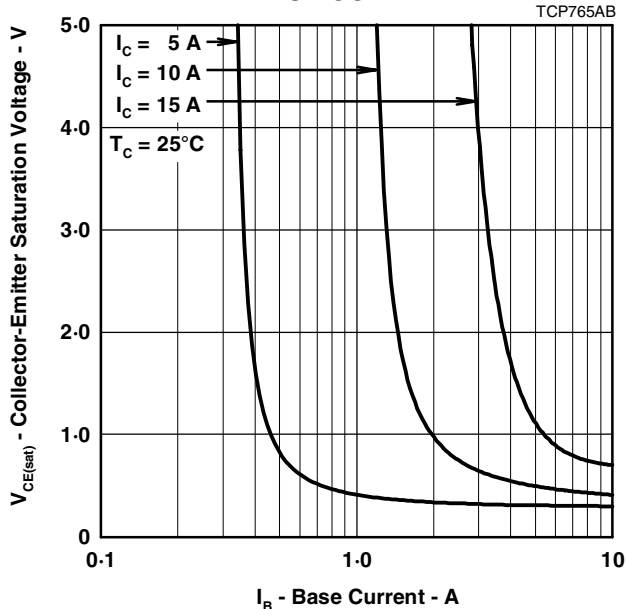


Figure 6.

COLLECTOR-EMITTER SATURATION VOLTAGE  
VS  
BASE CURRENT

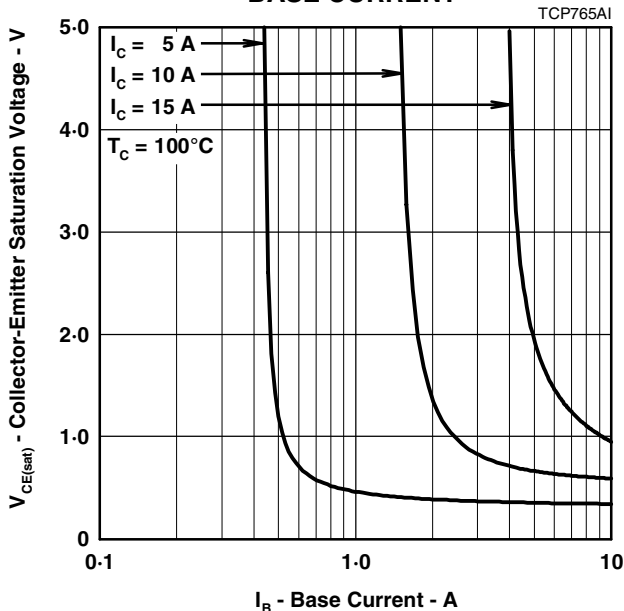


Figure 7.

BASE-EMITTER SATURATION VOLTAGE  
VS  
BASE CURRENT

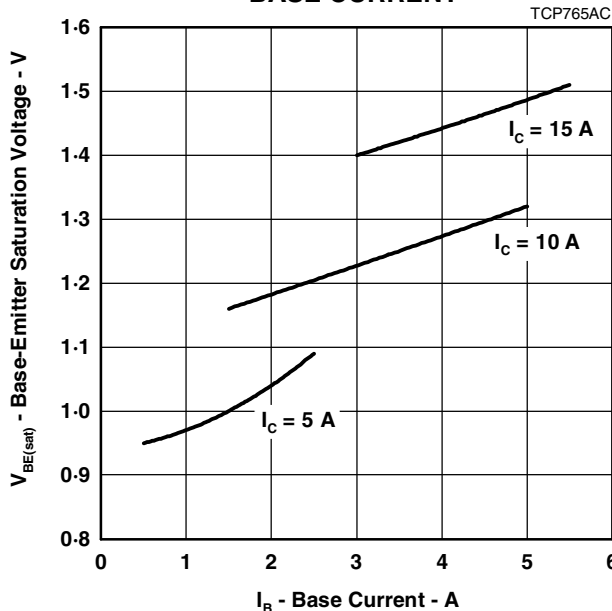


Figure 8.

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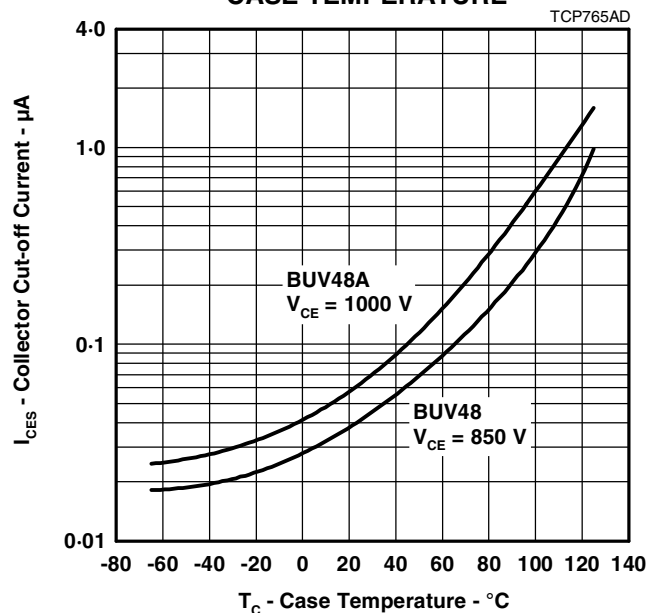
**TYPICAL CHARACTERISTICS**
**COLLECTOR CUT-OFF CURRENT**  
**VS**  
**CASE TEMPERATURE**


Figure 9.

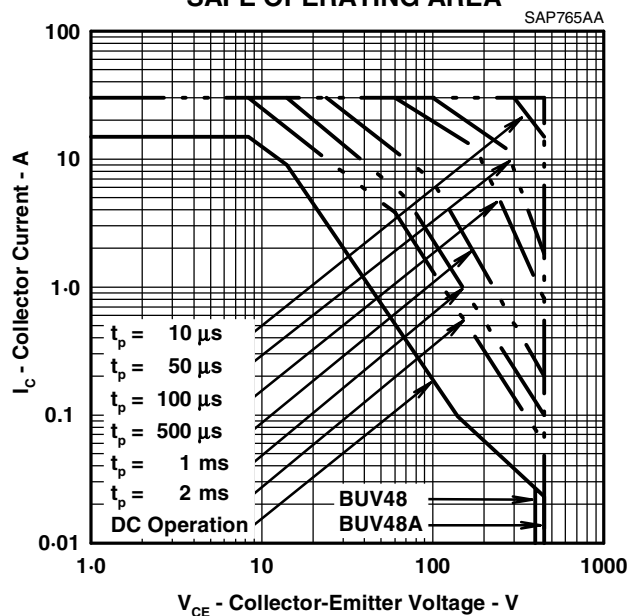
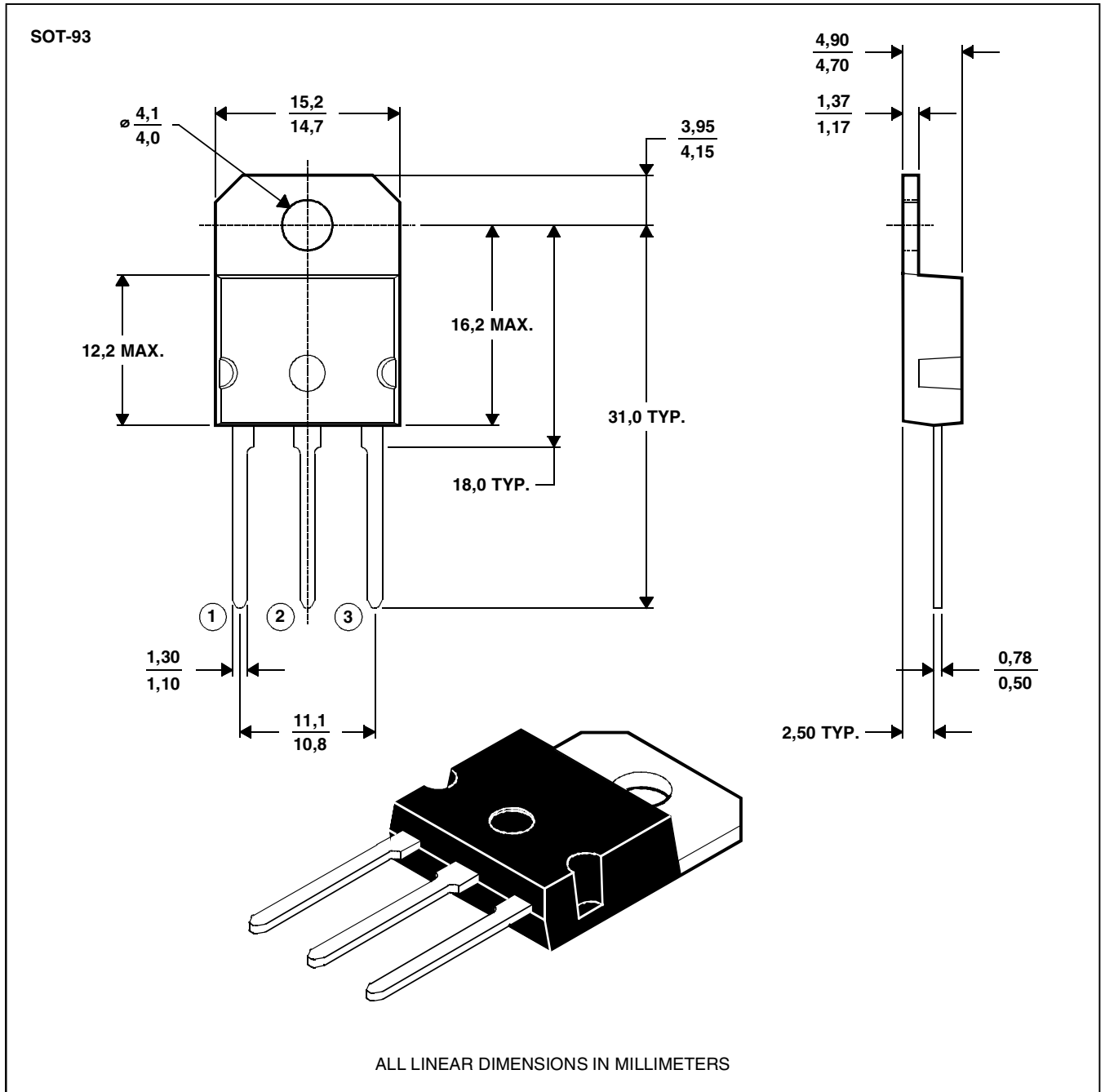
**MAXIMUM SAFE OPERATING REGIONS**
**MAXIMUM FORWARD-BIAS**  
**SAFE OPERATING AREA**


Figure 10.

**BOURNS®**
**MECHANICAL DATA**
**SOT-93**
**3-pin plastic flange-mount package**

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW

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